LARGE ELASTIC MOMENTUM CONDUCTION
MEMBER OF IC DEVICE SOCKET

BACKGROUND OF THE INVENTION

1. Field of the Invention

5   The present invention is related to an IC device socket, and more particularly to a large elastic momentum conduction member of IC socket.

2. Description of the Prior Art

Generally the structure of a terminal of an IC device, particularly a central process unit (CPU), may be classified into three types of arrays, respectively the Pin

10   Grid Array (P.G.A.), the Ball Grid Array (B.G.A.) and the Land Grid Array (L.G.A.).

As taught in USA Patent No. 5,456,613, a socket specific for the P.G.A. IC device is provided. However, the socket is very thick and fails to meet the requirement of being compact since the P.G.A. type of IC device is disposed of an extremely long terminal, and it takes a conduction member with a compatible height

15   to be embedded in the thick insulation plate for it to contact the terminal of the IC device and the conduction contact of the PCB.

Later the B.G.A. type of IC device has a reduced length since the terminal has been developed by changing the pin terminal of the P.G.A. type of IC device into a ball grid, e.g., tin ball or copper ball, such as the socket specific to the B.G.A. type

20   of IC device disclosed in US Patent No. 5,419,710.

The latest development of the L.G.A. type of IC device in flat land grid array allows a less complicated structure, lower production cost and better conduction results, such as those taught in US Patent Nos. 5,192,213; 5,199,889; 5,320,550; and 5,362,241 to provide many types of sockets in different structures.

25   To reduce the size of the IC device, the spacing between any two abutted contact terminals must be made narrower and denser, such as 1.27, 1.0, 0.8 and 0.5m is generally provided. Within such a small space, it is already very difficult to insert a conduction member. Since sufficient space for up and down elastic